

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments |
|---|------|-----|-------|--|--|------------------|----------|
| 6 | BRS | L6 | 58210 | (flat\$8 or planar\$4 or polish\$4 or CMP) same (bump or stud or ball) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB | 2003/08/26 16:04 | |
| 7 | BRS | L7 | 3940 | 6 same (reflow\$4 or re-flow\$4 or solder\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB | 2003/08/26 16:07 | |
| 8 | BRS | L8 | 1072 | 7 and (wirebond\$4 or (wir\$4 adj bond\$4)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB | 2003/08/26 16:08 | |
| 9 | BRS | L9 | 981 | 8 and (UBM or (under adj (bump or ball) or metal\$8)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB | 2003/08/26 16:09 | |